

# The Interaction of the Dipole Moment of The Water Molecule with the Interface States of the Cuprous Oxide/Cupric Oxide Junction

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## Abstract

An Au/CuO/Cu<sub>2</sub>O/Cu sandwich structure has been obtained by growing successive Cu<sub>2</sub>O and CuO layers on a Cu sheet. A gold metal contact was formed CuO side at pressure of  $1 \times 10^{-6}$  Torr. Current-voltage characteristics and capacitance of the system were seen to change over a great extent due to the presence of humidity. The effect of the humidity on Au/CuO/Cu<sub>2</sub>O/Cu is explored through the effect of water's dipole moment.

## Introduction

CuO was first used as a humidity sensor by Ming [1] during his studies of thick films. However, there have been a number of works on humidity sensing structures containing CuO in their construction such as the CuO/ZnO thin film heterojunction [1-7]. These works indicate that oxides of copper might be useful for the construction of humidity sensors, and thus their properties need further study.

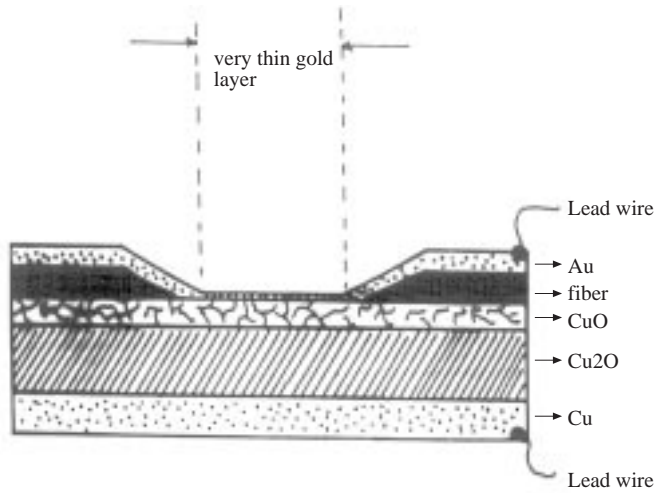
For this purpose a structure of Au/CuO/Cu<sub>2</sub>O/Cu sandwich structure was produced and both its current-voltage characteristics and capacitance values were measured at various humidities. The next section is a description of experimental details and we discuss the results in section 3.

## Experiment

We started by obtaining a very clean copper surface and this was done by first chemically cleaning the sample using deionized water, the acetone(CH<sub>3</sub>COCH<sub>3</sub>) and a mixture

of deionized water and nitric acid (50%  $\text{H}_2\text{O}$ +50%  $\text{HNO}_3$ ) in standard way. The sample, with dimensions  $10\text{mm}\times 10\text{mm}$  and  $200\ \mu\text{m}$  thickness, was put in the oven [4] for 10 minutes at  $700\ ^\circ\text{C}$  with dry hydrogen gas passing over it. Cuprous oxide layer was grown by hanging the sample in the furnace at  $1040\ ^\circ\text{C}$  temperature for 5 minutes and then cooled to room temperature. The sample was then annealed at  $600\ ^\circ\text{C}$  then cooled outside the oven in the room [7]. Afterwards an n/p junction was formed within the  $\text{Cu}_2\text{O}$  layer by quenching it in deionized water. The formed  $\text{Cu}_2\text{O}$  was  $32\ \mu\text{m}$  thick and

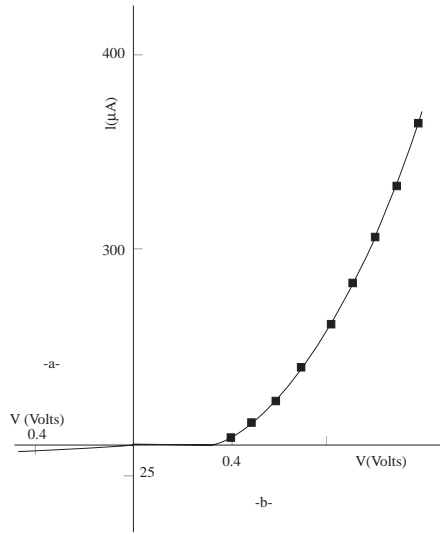
$\text{CuO}$  layer's thickness was  $1\ \mu\text{m}$ . We proceeded by taking one side of the sample ( $\text{CuO}/\text{Cu}_2\text{O}/\text{Cu}$ ) and fixing it on a fiber holder by araldite, and then a lead was soldered to the copper side. A gold Ohmic contact was created on the  $\text{CuO}$  side at a vacuum of  $1\times 10^{-6}$  Torr. (Fig.1).



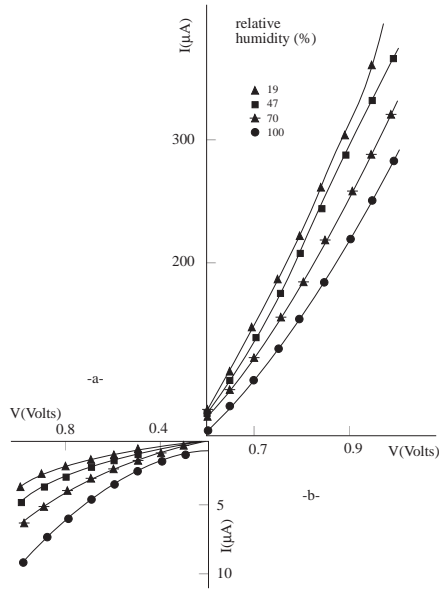
**Figure 1.** The structure of  $\text{Au}/\text{CuO}/\text{Cu}_2\text{O}/\text{Cu}$  device.

## Result and discussion

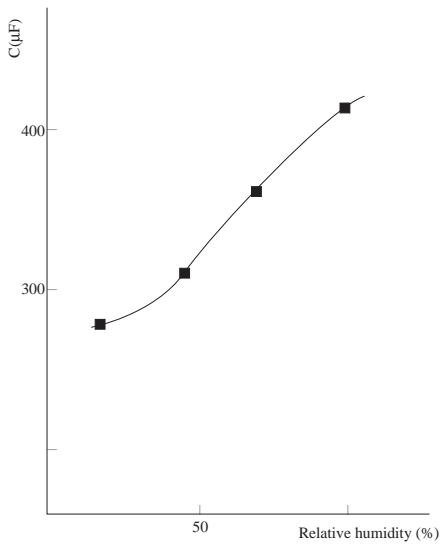
The types of  $\text{Cu}_2\text{O}$  and  $\text{CuO}$  were determined both by four probe method and by galvanometric method. The  $\text{Cu}_2\text{O}$  samples were p-type and  $\text{CuO}$  n-type consistent with the literature [8]. The current-voltage characteristics of the quenched  $\text{Au}/\text{CuO}/\text{Cu}_2\text{O}/\text{Cu}$  structure (Fig.2) showed that an n/p junction had been formed within the  $\text{Cu}_2\text{O}$  layer. To check this conclusion we produced two structures, one  $\text{Au}/\text{CuO}(\text{n-type})/\text{Cu}$  and other  $\text{Au}/\text{Cu}_2\text{O}(\text{quenched})/\text{Cu}$  from which, it was seen that only the latter had the diode behavior. From the polarity of the applied voltage we concluded with the behavior shown in Fig.6 that the p-type portion of the n/p junction was located near the copper and n-type region near the  $\text{CuO}$  layer. Under increasing humidity we observed a large increase in the forward current, while the reverse current decreased (Figs. 3, 4 and 5).



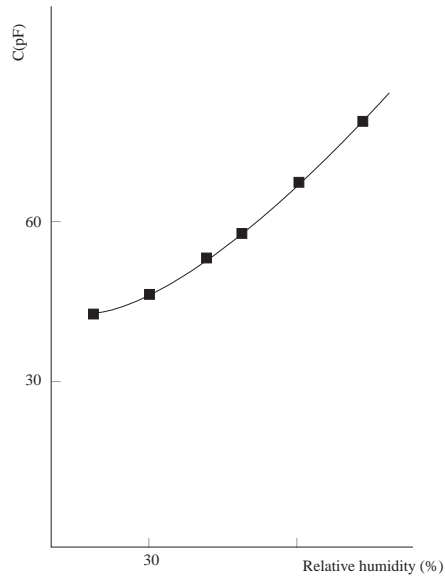
**Figure 2.** Current-voltage characteristic of Au/CuO/Cu<sub>2</sub>O/Cu structure at 20°C for a constant humidity, a) reverse bias; (+)Au/CuO/Cu<sub>2</sub>O/Cu(-), b) (-)Au/CuO/Cu<sub>2</sub>O/Cu(+); forward bias.



**Figure 3.** Current-voltage characteristic of Au/CuO/Cu<sub>2</sub>O/Cu structure versus relative humidity at 20°C, a) reverse bias, b) forward bias.

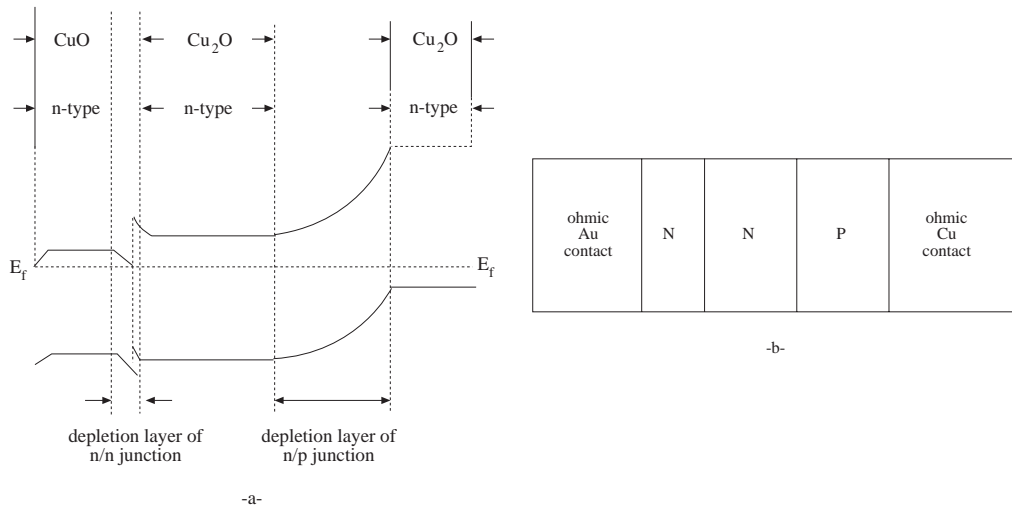


**Figure 4.** Current-relative humidity characteristic of Au/CuO/Cu<sub>2</sub>O/Cu structure at 20°C for 1.0 Volt forward bias.



**Figure 5.** Capacitance of Au/CuO/Cu<sub>2</sub>O/Cu structure at 1 KHz versus relative humidity.

The effect of humidity on the Au/CuO/Cu<sub>2</sub>O/Cu sandwich structure can be explained by the help of an n/n heterojunction created by CuO with band gap of 2.0 eV. and Cu<sub>2</sub>O with band gap 1.95 eV. at the CuO/Cu<sub>2</sub>O interface [9-10]. As is seen from Figure 6 the CuO/Cu<sub>2</sub>O interface contains an n/n heterojunction with a small diffusion barrier height. The pinholes in gold film and the grainy structure of the cupric oxide(CuO) allow the water molecules to diffuse into the n/n heterojunction which contains surface states. Dipole moment of the water molecules interacts with these interface states and alters the electrical potential profile in n/n heterojunction , resulting in the electrical charge distribution in depletion layer of the n/n heterojunction being rearranged. As a result the barrier height of n/n heterojunction is changed and the capacitance and current-voltage characteristics of the Au/CuO/Cu<sub>2</sub>O/Cu sandwich structure are modified by the humidity [11]. The theoretical explanation of humidity effect on the interface states , as well as more intense measurements , will be carried out in our forthcoming work. The results will be published in a detailed paper later.



**Figure 6.** a) Energy band-diagram proposed for CuO/Cu<sub>2</sub>O sandwich structure and b) representation of Au/CuO/Cu<sub>2</sub>O/Cu sandwich structure.

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